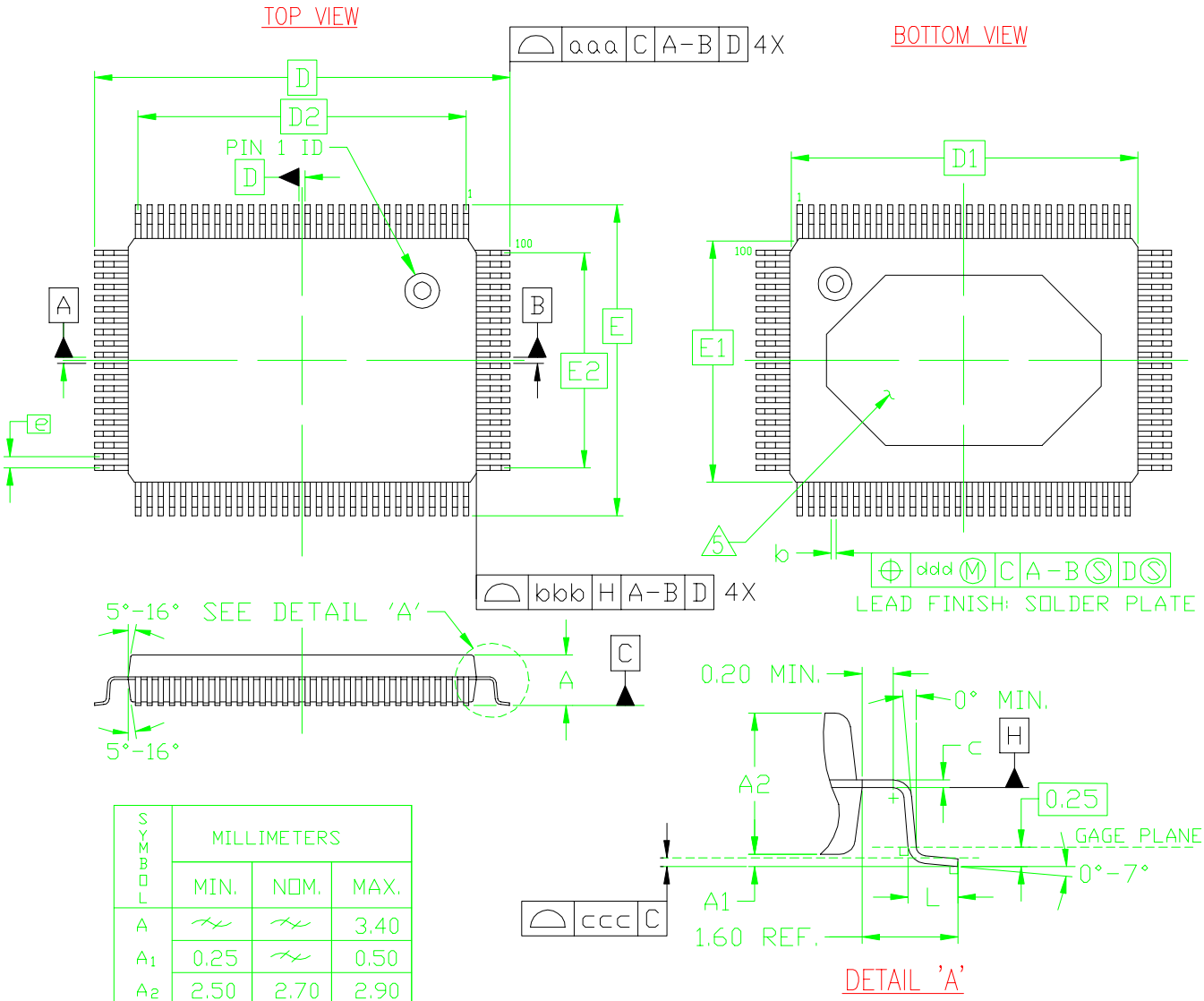
PQFP (PQ100) Package
HQFP (Heat Sink) (HQ100) Package



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A			3.40
A_1	0.25		0.50
A_2	2.50	2.70	2.90
D	23.20 BSC		
D_1	20.00 BSC		
D_2	18.85 REF.		
E	17.20 BSC		
E_1	14.00 BSC		
E_2	12.35 REF.		
L	0.73	0.88	1.03
e	0.65 BSC		
b	0.22		0.40
c	0.13		0.23
aaa			0.25
bbb			0.20
ccc			0.10
ddd			0.13

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
2. DIMENSIONS 'D1' AND 'E1' DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25mm PER SIDE.
3. THE TOP OF PACKAGE MAY BE EQUAL TO OR SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.
4. PACKAGE CONFORMS TO JEDEC OUTLINE MS-022-GC1
5. THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS 'HQ'.

100-PIN PQFP (PQ100)
100-PIN HEAT SINK PQFP (HQ100)

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